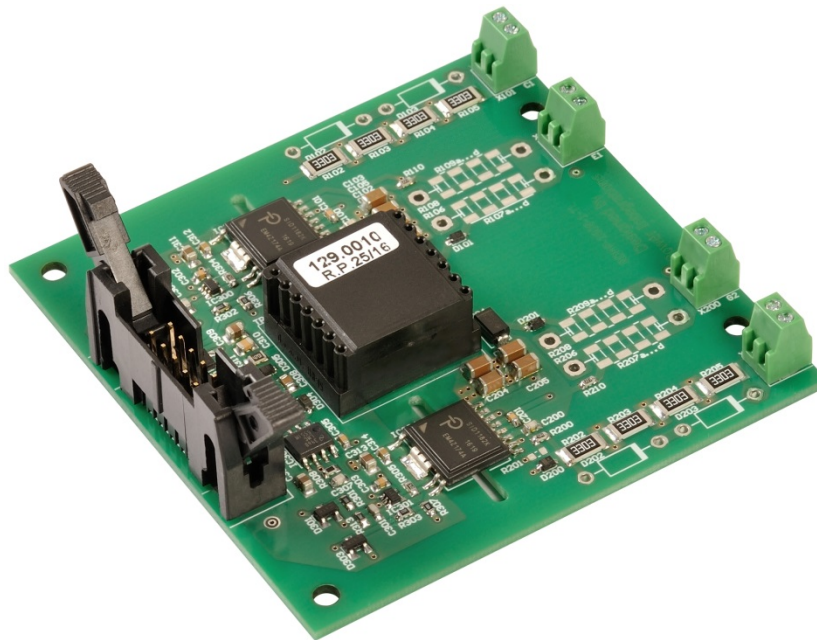


General Purpose Base Board for SCALE™-iDriver SID1182K

Application	General purpose drives, UPS, solar power and others
Specification	Suitable for IGBT power modules in various housings Up to 800V DC-link voltage Electrical interfaces Interlock Short-circuit detection with Advanced Soft Shut Down
Author	High-Power Application Engineering Department
Document Number	RDHP-1608
Revision¹	A.1



¹ The letter refers to the hardware revision. The number refers to the documentation revision.

Scope

This application proposal provides a circuit design for a general purpose base board for driving various IGBT power modules.

The main features of the design are:

- Suitable for IGBT power modules in various housings such as 17mm dual, 17mm six-pack, 62mm, PrimePACK™, etc. with a maximum blocking voltage of 1200V
- Short-circuit detection with Advanced Soft Shut Down (ASSD)
- Electrical command inputs and status outputs
- 0V/5V command input logic
- 0V/5V status output logic
- Minimum pulse suppression
- Interlock of command inputs
- 5V supply voltage
- Single PCB solution with soldered-in gate driver IC

Intellectual Property Licensing

The design proposal, products and applications illustrated herein (including transformer construction and circuits external to the products) may be covered by one or more U.S. and foreign patents, or potentially by pending U.S. and foreign patent applications assigned to Power Integrations.

A complete list of Power Integrations patents may be found at <https://www.power.com/>.

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Application Conditions

The design is proposed for the following application conditions:

- General purpose applications and IGBT power modules
- Adaptations such as adjustment of gate resistors can easily be done
- Up to 8A peak gate current
- Up to 1W per channel

Design Description

In addition to the following design description, reference to the datasheet of the gate driver IC family is recommended.

Gate Resistors

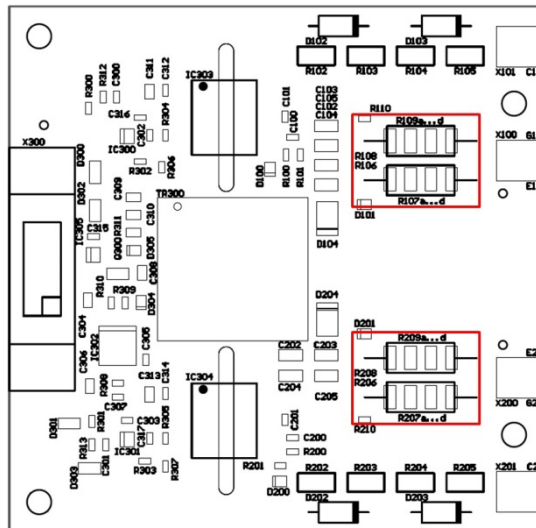
Gate resistor values are not explicitly given as they depend on the IGBT power module used and on the application. Gate resistors of either SMD (size 1206) or THT (size PR02) package can be selected.

Turn-on gate resistors:

Channel	SMD Package	THT Package
1	R107a ... R107d	R106
2	R207a ... R207d	R206

Turn-off gate resistors:

Channel	SMD Package	THT Package
1	R109a ... R109d	R108
2	R209a ... R209d	R208



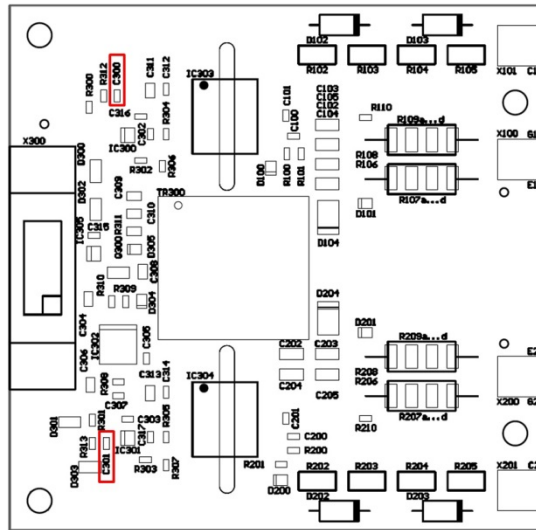
The gate resistors must be determined and assembled by the user.

V_{CEsat} Monitoring

SID1182K gate driver ICs from Power Integrations provide sense inputs for monitoring IGBT short-circuit conditions.

This design offers a V_{CEsat} monitoring function using either a resistor network or high-voltage diodes based on the same layout (Power Integrations recommends using the resistor network implementation as the preferred solution). The assembly variants of either implementation are described in the following table:

Implementation	C100, C200	R100, R200	R101, R201	R102 ... R105, R202 ... R205	D102, D103, D202, D203	D100, D200
Resistor network	33pF	120kΩ	n.a.	330kΩ	n.a.	BAS416
High-voltage diodes	100pF	330Ω	47kΩ	n.a.	UF4007	n.a.



Recommended values of C300 and C301 are in the range of 1nF ($\tau_x = 99\text{ns}$) to 3.3nF ($\tau_x = 327\text{ns}$), depending on actual application conditions.

Blocking Time

During the blocking time, which is set to typically 10 μs , the gate driver IC ignores incoming command signals. The blocking time starts once a fault was detected by the gate driver IC's secondary side (undervoltage lock-out or a short-circuit event) or when an undervoltage condition ends on the primary side.

For further details refer to the datasheet of the gate driver SID1182K.

Interfaces

Electrical Interfaces

X300		
Pin	Designation	Description
1	V5	5V supply (referenced to GND)
3	SO2	Status output channel 2
5	INB	Command input channel 2
7	SO1	Status output channel 1
9	INA	Command input channel 1

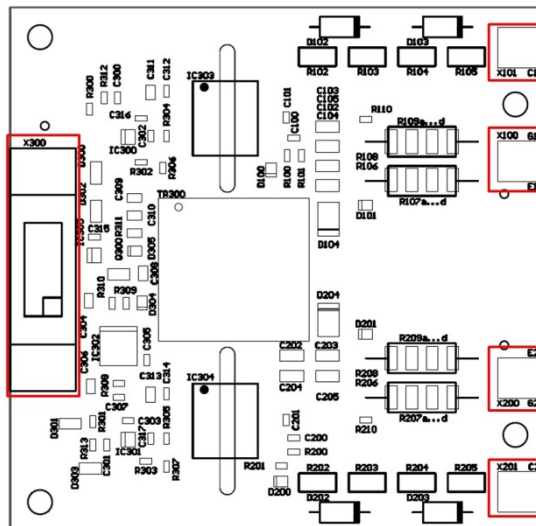
X300		
Pin	Designation	Description
2	GND	Ground
4	GND	Ground
6	GND	Ground
8	GND	Ground
10	GND	Ground

X100		
Pin	Designation	Description
1	E1	Emitter channel 1
2	G1	Gate channel 1

X101		
Pin	Designation	Description
1	C1	Collector channel 1
2	C1	Collector channel 1

X200		
Pin	Designation	Description
1	G2	Gate channel 2
2	E2	Emitter channel 2

X201		
Pin	Designation	Description
1	C2	Collector channel 2
2	C2	Collector channel 2

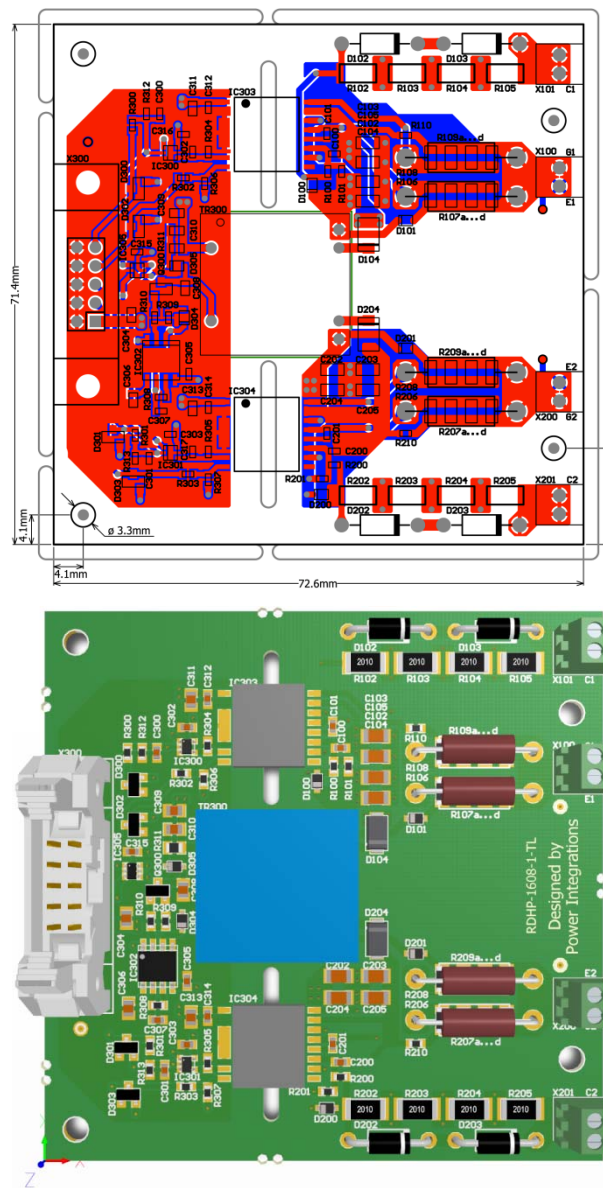


CAD Data

The set of CAD data, which includes the circuit schematics, Gerber files, assembly drawing, BOM and Pick-and-Place file are available as separate documents bundled together with this documentation.

Layout Example

An example for a suitable layout is shown in the following picture. The recommended PCB thickness is 1.55mm.



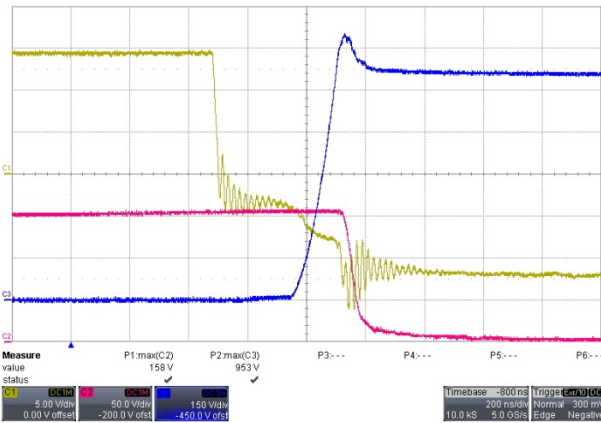
Switching Characteristic

Turn-On/Off

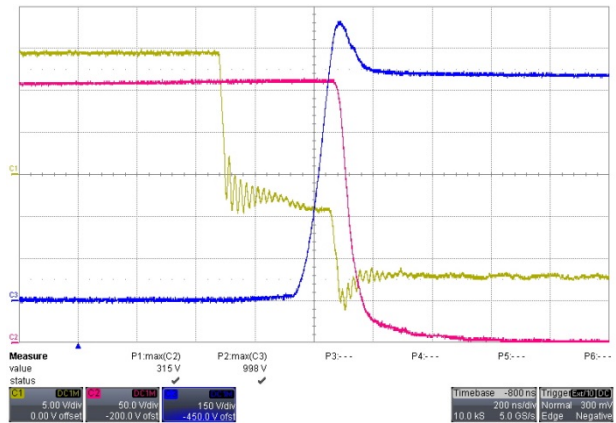
The measurement examples shown with the IGBT power module FF150R12YT3 from Infineon Technologies ($R_{Gon} = 2.4\Omega$ and $R_{Goff} = 2.4\Omega$) were carried out in a double-pulse test using a half-bridge topology setup at room temperature with an initial DC-link voltage of $800V_{DC}$. The adjusted load current is either $150A$ (I_{nom}) or $300A$ ($2x I_{nom}$).

Channel assignment:

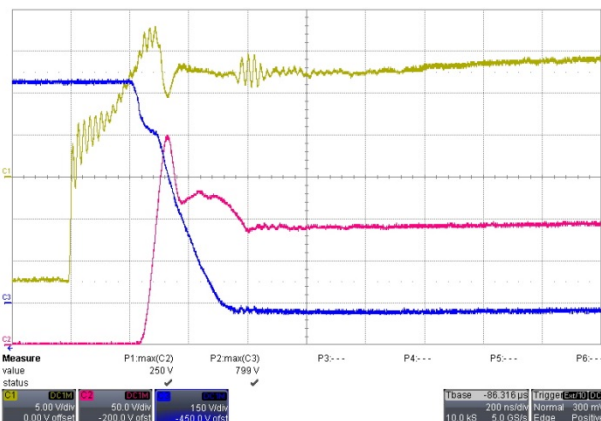
- Channel C1: Gate-emitter voltage
- Channel C2: Collector current [$1V \triangleq 1A$]
- Channel C3: Collector-emitter voltage



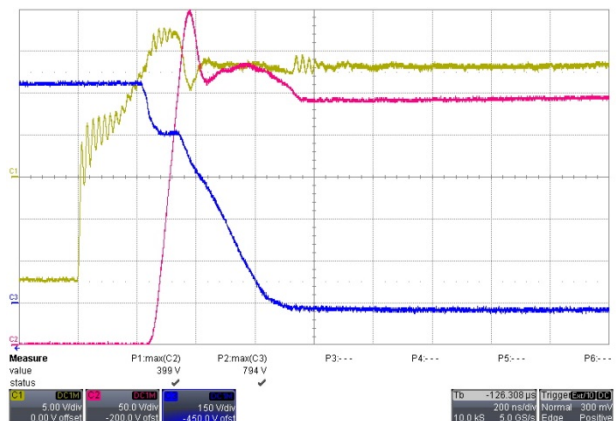
Turn-off bottom side (I_{nom})



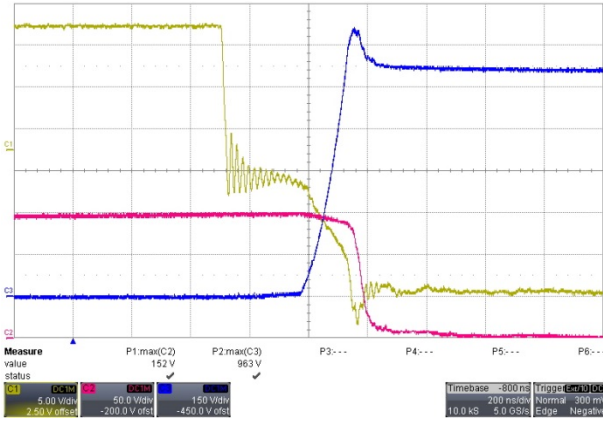
Turn-off bottom side ($2x I_{nom}$)



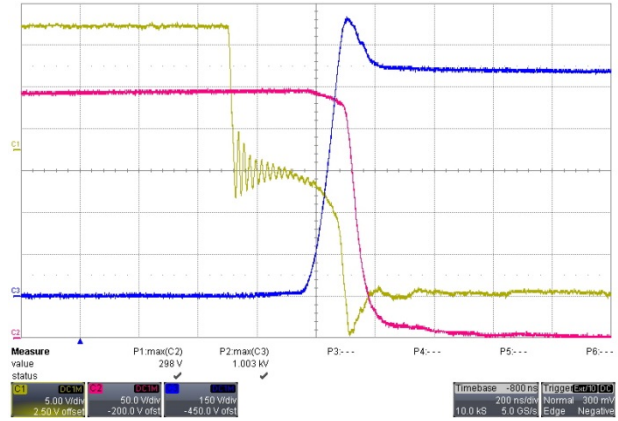
Turn-on bottom side (I_{nom})



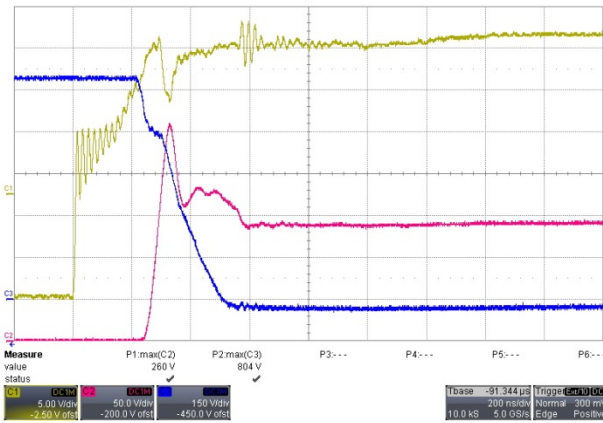
Turn-on bottom side ($2x I_{nom}$)



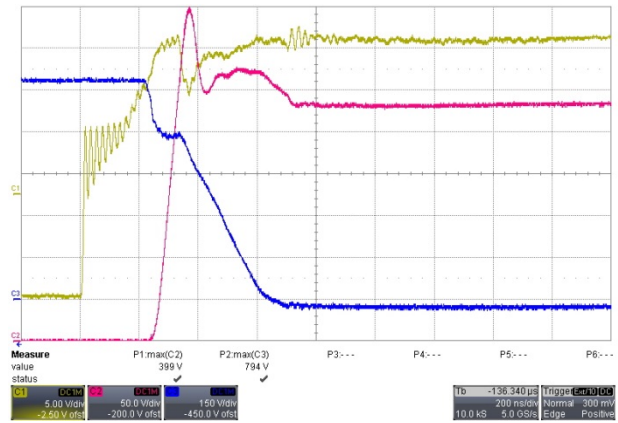
Turn-off top side (I_{nom})



Turn-off top side ($2x I_{nom}$)



Turn-on top side (I_{nom})



Turn-on top side ($2x I_{nom}$)

Short-Circuit

The measurement examples shown with the IGBT power module FF150R12YT3 from Infineon Technologies ($R_{Gon} = 2.4\Omega$ and $R_{Goff} = 2.4\Omega$) were carried out at room temperature with an initial DC-link voltage of $800V_{DC}$.

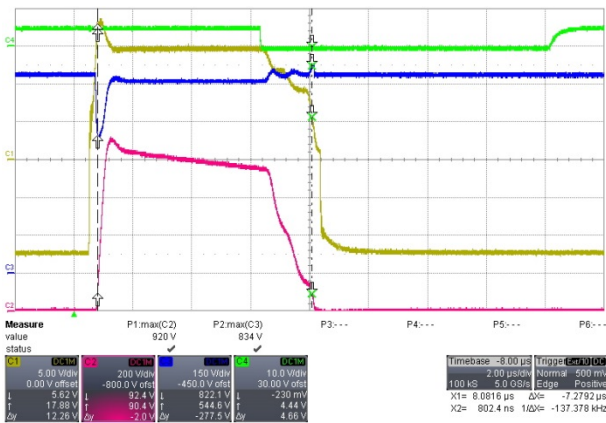
Channel assignment:

Channel C1: Gate-emitter voltage

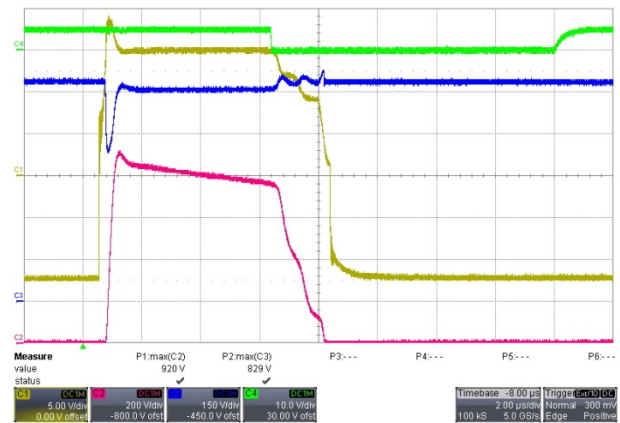
Channel C3: Collector-emitter voltage

Channel C2: Collector current ($1V \triangleq 1A$)

Channel C4: Status output



Bottom side



Top side

Handling

To avoid possible failures caused by ESD, a handling- and assembly-process with persistent ESD protection is necessary /2/.

References

- /1/ SID11x2K SCALE-iDriver Family Data Sheet, Power Integrations
- /2/ Application Note AN-0902, "Avoiding ESD with CONCEPT Drivers", Power Integrations

Technical Support

Power Integrations provides expert help with your questions and problems:

Website <http://www.power.com/igbt-driver/go/support>

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